

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D $T_A = +25^\circ C$
30V	52m Ω @ $V_{GS} = 10V$	4A
	65m Ω @ $V_{GS} = 4.5V$	3A
	85m Ω @ $V_{GS} = 2.5V$	2A

Applications

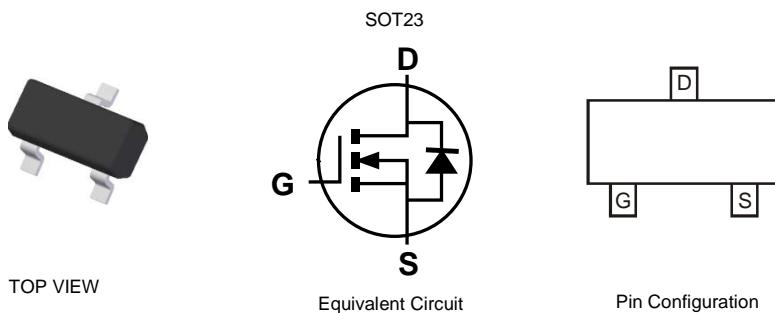
- DC-DC Converters
- Power Management Functions
- Battery Operated Systems and Solid-State Relays

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)



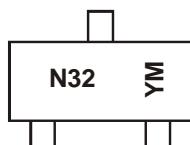
Ordering Information (Note 4)

Part Number	Case	Packaging
DMG3402L-7	SOT23	3000/Tape & Reel
DMG3402L-13	SOT23	10000/Tape & Reel

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



N32 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

Year	2012	2013	2014	2015	2016	2017	2018					
Code	Z	A	B	C	D	E	F					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 12	V
Drain Current (Note 5)	I_D	4.0	A
Body-Diode Continuous Current (Note 5)	I_S	1.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.4	W
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ\text{C}$ (Note 5)	$R_{\theta JA}$	90	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 30\text{V}$, $V_{GS} = 0\text{V}$
Gate-Body Leakage	I_{GS}	—	—	± 100	nA	$V_{GS} = \pm 12\text{V}$, $V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(\text{th})}$	0.6	—	1.4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	—	52	$\text{m}\Omega$	$V_{GS} = 10\text{V}$, $I_D = 4\text{A}$
		—	—	65		$V_{GS} = 4.5\text{V}$, $I_D = 3\text{A}$
		—	—	85		$V_{GS} = 2.5\text{V}$, $I_D = 2\text{A}$
Forward Transconductance	$ Y_{fs} $	—	6.6	—	S	$V_{DS} = 5\text{V}$, $I_D = 3.1\text{A}$
Source-Drain Diode Forward Voltage	V_{SD}	—	—	1.16	V	$V_{GS} = 0\text{V}$, $I_S = 2.0\text{A}$
DYNAMIC CHARACTERISTICS (Note 7)						
Gate Resistance	R_g	—	2.2	—	Ω	$V_{DS} = 0\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$
Total Gate Charge (10V)	Q_g	—	11.7	—	nC	$V_{GS} = 10\text{V}$, $V_{DS} = 15\text{V}$, $I_D = 4\text{A}$
Total Gate Charge (4.5V)	Q_g	—	5.5	—	nC	$V_{GS} = 10\text{V}$, $V_{DS} = 15\text{V}$, $I_D = 4\text{A}$
Gate-Source Charge	Q_{gs}	—	1.1	—	nC	
Gate-Drain Charge	Q_{gd}	—	1.8	—	nC	
Turn-On Delay Time	$t_{D(\text{on})}$	—	1.9	—	ns	
Turn-On Rise Time	t_r	—	1.6	—	ns	
Turn-Off Delay Time	$t_{D(\text{off})}$	—	10.3	—	ns	
Turn-Off Fall Time	t_f	—	2.0	—	ns	
Input Capacitance	C_{iss}	—	464	—	pF	
Output Capacitance	C_{oss}	—	49.5	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	43.8	—	pF	

Notes:

5. Device mounted on FR-4 PCB. $t \leq 5$ sec.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to production testing.

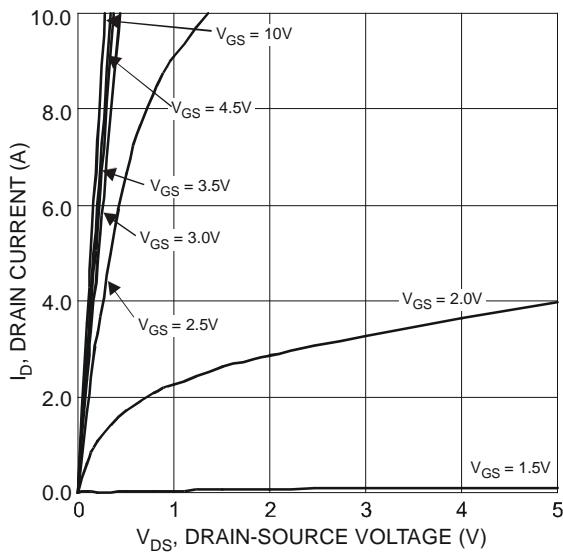


Figure 1 Typical Output Characteristics

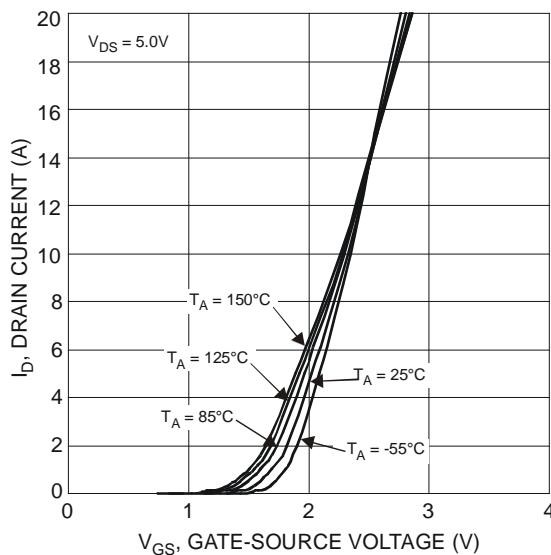


Figure 2 Typical Transfer Characteristics

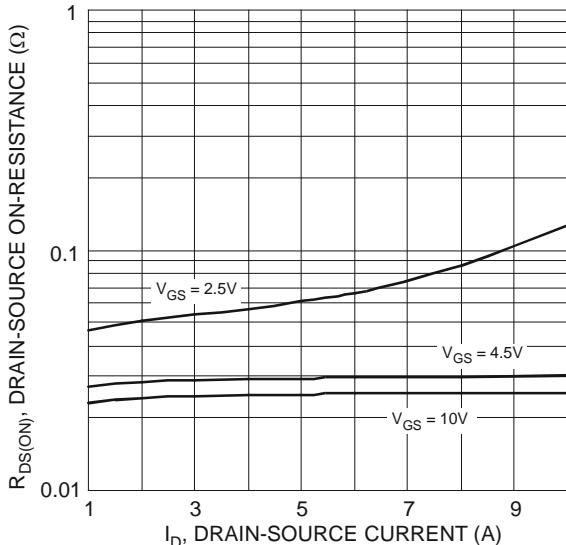


Figure 3 Typical On-Resistance vs.
Drain Current and Gate Voltage

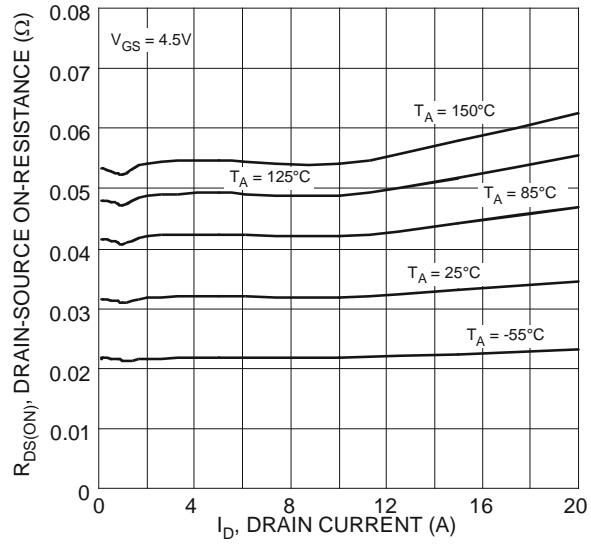


Figure 4 Typical On-Resistance vs.
Drain Current and Temperature

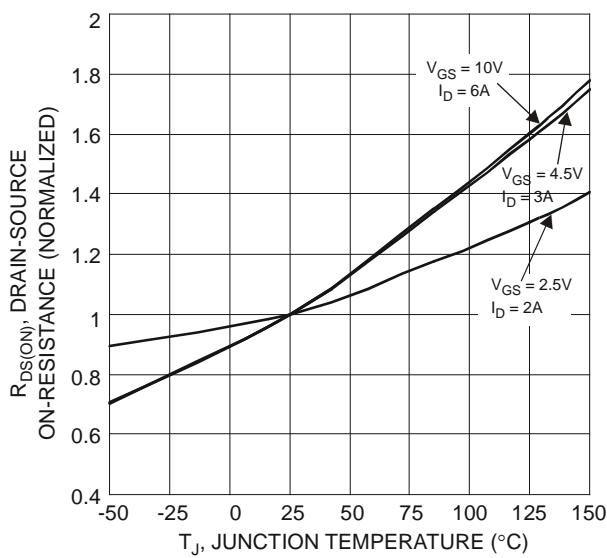


Figure 5 On-Resistance Variation with Temperature

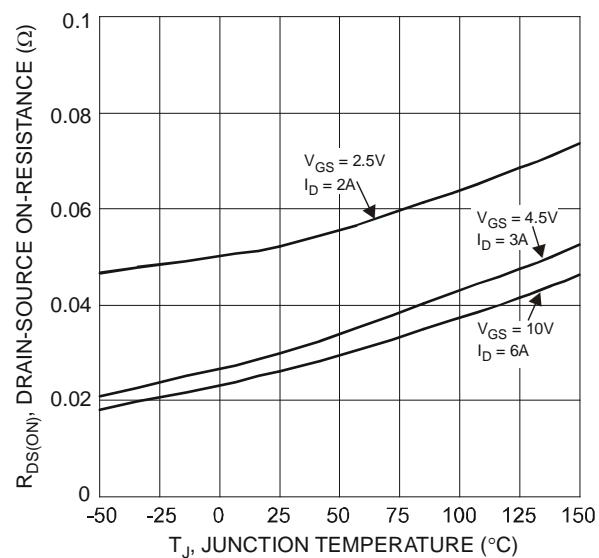


Figure 6 On-Resistance Variation with Temperature

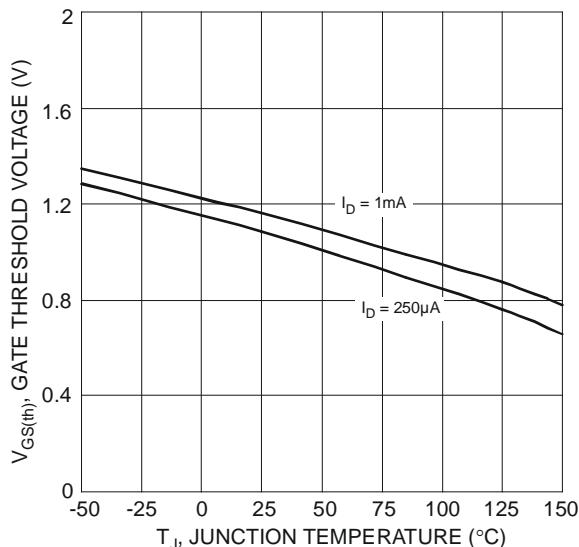


Figure 7 Gate Threshold Variation vs. Ambient Temperature

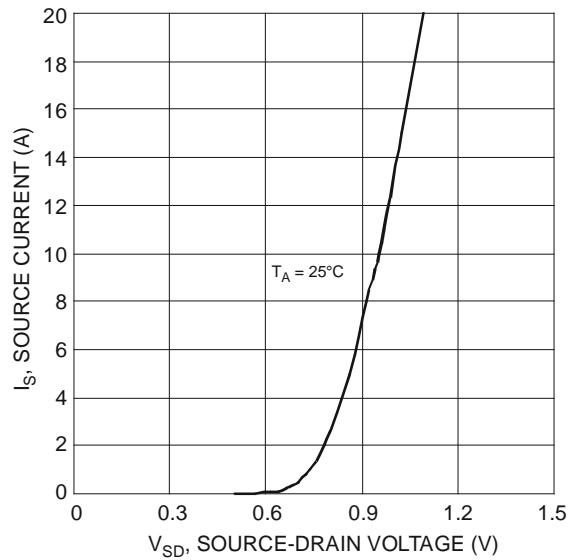


Figure 8 Diode Forward Voltage vs. Current

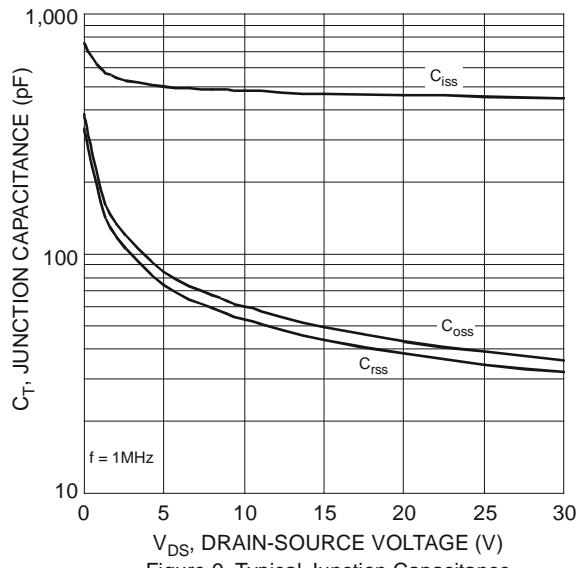


Figure 9 Typical Junction Capacitance

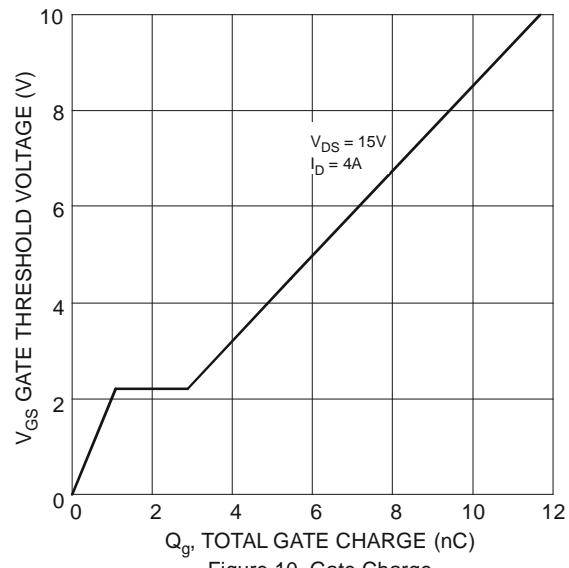


Figure 10 Gate Charge

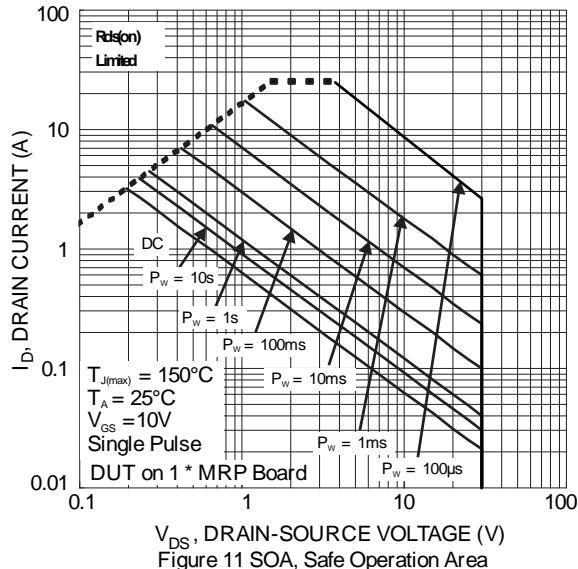


Figure 11 SOA, Safe Operation Area

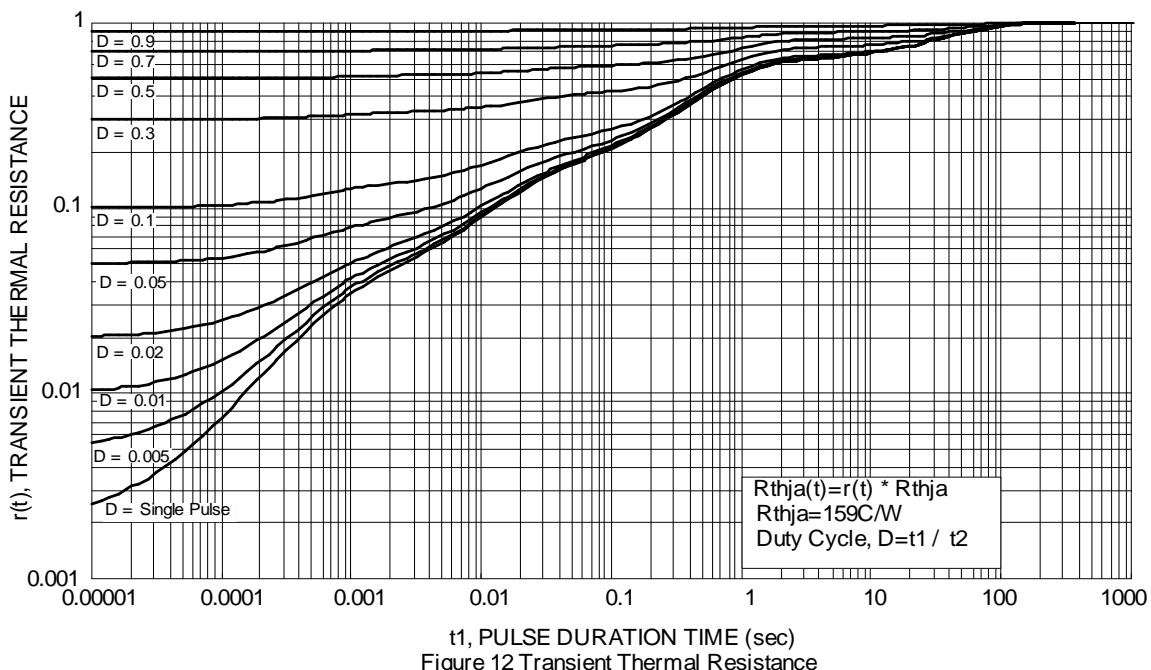
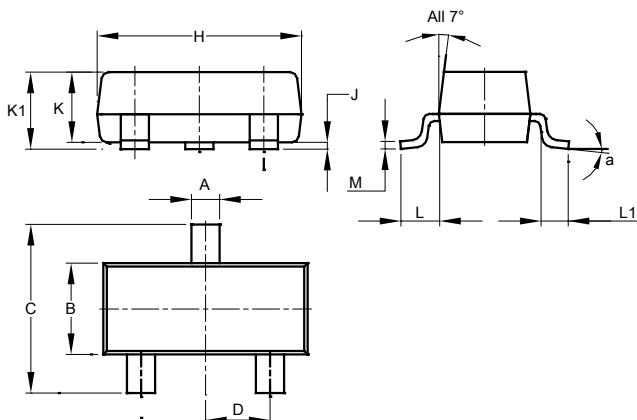


Figure 12 Transient Thermal Resistance

Package Outline Dimensions

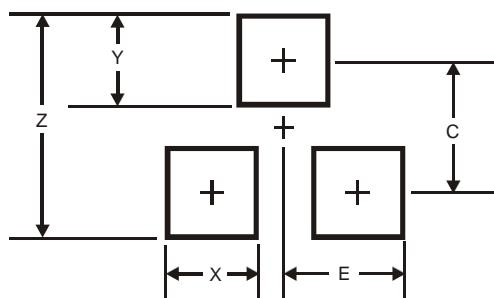
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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